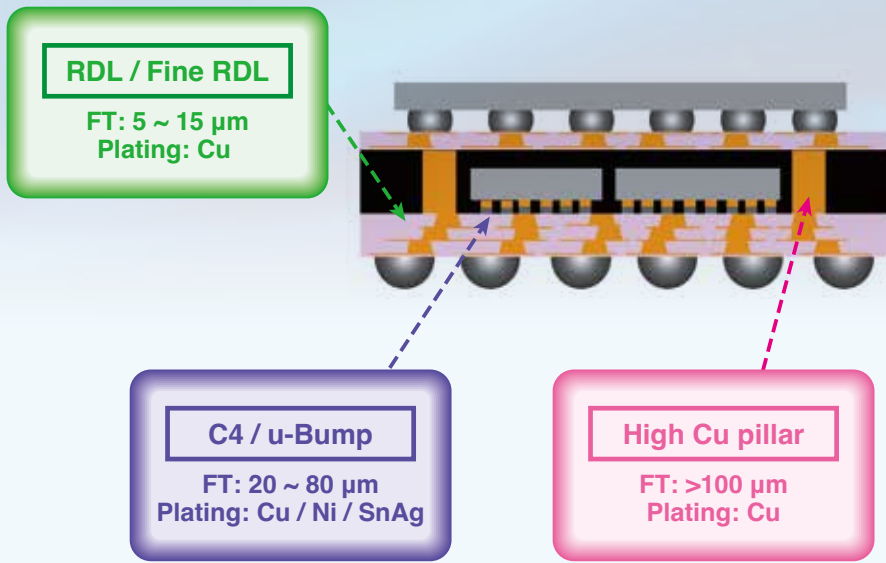
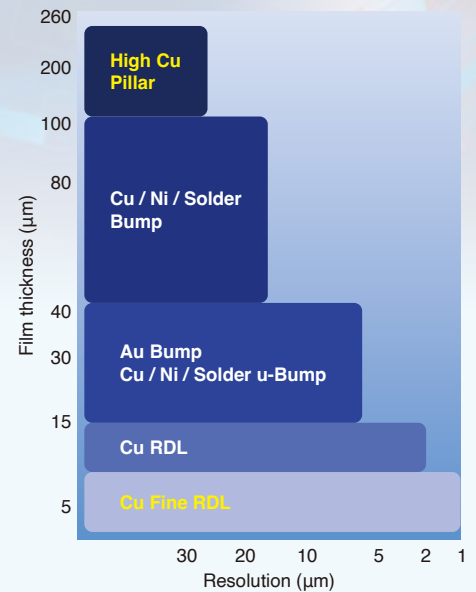


JSR Thick Layer Photoresist THB series

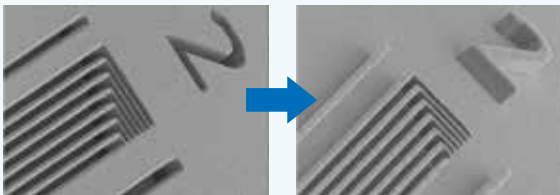


Product Line up



Cu RDL

Nega Type



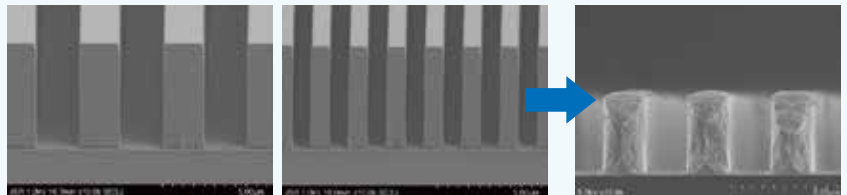
Cu Plate
THB stripped

Cu Fine RDL

Posi Type

2.0 μm L/S

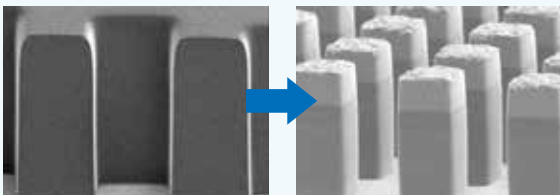
0.9 μm L/S



Film Thickness: 5 μm

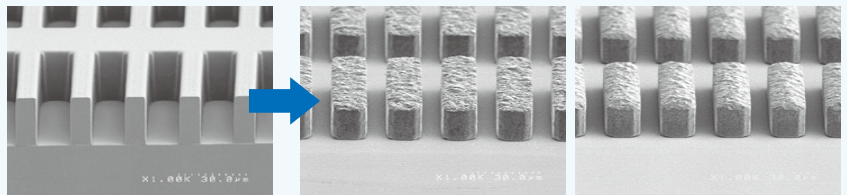
Cu Plate
THB stripped

Cu / Ni / Solder Bump



Cu / Ni / SnAg Plate
THB stripped

Au Bump



Cyanide Au Plate
THB stripped

Non-cyanide Au Plate
THB stripped

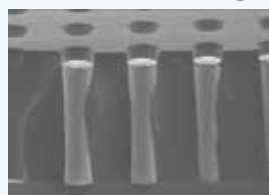
High Cu Pillar

20μm φ



Film Thickness: 170 μm

After Cu Plating



Cu height 190 μm / 50 μm φ

After Stripping

